# BB810

# Fasson ®

## POLYIMIDE I WH TC14
## S8088-BG50WH

### Facestock

A durable polyimide film with a high-temperature resistant, highly opaque, semi-matt white topcoat.

| | | |
|---|---|---|
| Basis Weight | 75 g/m² | ISO 536 |
| Caliper | 46 µm | ISO 534 |
| Maximum Peak Temperature | 260 °C | |

### Adhesive

S8088 is a high temperature acrylic adhesive with excellent heat and chemical resistance.

### Liner

BG50 white, a supercalendered glassine paper.

| | | |
|---|---|---|
| Basis Weight | 80 g/m² | ISO 536 |
| Caliper | 68 µm | ISO 534 |

### Laminate

| | | |
|---|---|---|
| Total Caliper | 143 µm±10% | ISO 534 |

### Performance Data

| | | |
|---|---|---|
| Initial Tack | 5 N/25mm | FTM 9 glass |
| Peel Adhesion 90° | 5 N/25mm | FTM 2 st.st.; 24 hrs. |
| Min. Application Temp. | 10 °C | |
| Service Temperature | -40 °C to 180 °C | |
| Adhesive Coat Weight | 25 g/m² | FTM12 |
| Adhesive Type | Solvent Acrylic | |

### Adhesive Performance

S8088 was specially developed for labeling printed circuit boards prior to soldering.

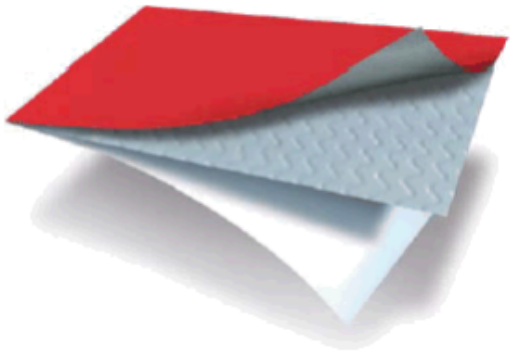
### Applications and Use

This polyimide label material is optimised for thermal transfer printing and specially formulated to withstand the high temperatures of the reflow process. It can be applied to all lead and lead-free soldering processes in the market, but is not recommended for wave solder applications when applied to the bottom side of the PCB.

Depending on the circumstances, the material can withstand peak temperatures of up to +300°C without color change or loss of adhesion. Application testing is highly recommended. The engineered topcoat in combination with the appropriate thermal tranfer ribbon features excellent scuff, scratch high temperature and solvent resistance.

### Conversion and Printing

The high performance topcoat was specially designed for thermal transfer printing, especially suitable for precise barcodes. It is also suitable for conventional printing techniques if necessary. The choice of thermal transfer ribbons influences the overall print quality and environmental resistance. For best results resin ribbons should be used (for example DNP R300, R510, Armor AXR8 or Ricoh B110CR). Testing is highly recommended.



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*This is an automatically generated datasheet. All data to be considered as typical values and subject to change without prior notice. Further testing is always recommended.*
*If you would like to make a suggestion or comment on this datasheet, please send an email to datasheet.mgmt@eu.averydennison.com*

This product can be diecut and stripped at high speeds on most web-fed presses. Hardened and sharp dies, preferably in flat-bed, are important to ensure smooth conversion.

Due to the low caliper of the face material automatic dispensing has to be tested.

## Compliance and Approvals

This product is UL recognized (UL 969). The UL file number is MH27538.

## Shelf Life

To obtain optimal performance, use this product within two years of the date of manufacture, under storage conditions as defined by FINAT (20-25°C; 40-50%RH). Prolonged storage outside these conditions might reduce the shelf life.

**Appendix**

## UL recognition

This product meets the requirements as stated in UL 969 and is UL recognized for indoor use.
The UL file number is MH27538. For specific information on approved conditions, see appendix.

## Performance Data

Note: the following technical data should be considered representative or typical only and should not be used for specification purposes.

### Peel Adhesion:

FTM1: 180°, 300 mm/min, dwell time: 48 hours

| Surface | dwell time 20 min (N/25mm) | dwell time 24 hrs (N/25mm) |
|---|---|---|
| Epoxy Printed Circuit Board | 4,5 | 7,0 |
| Stainless Steel | 4,5 | 6,5 |

### Short term high temperature resistance:

The thermal transfer printed label material has been tested on Epoxy Printed Circuit Board. A typical reflow lead and lead free solder profile with a maximum temperature peak of 235°C / 255°C has been processed.
No visible changes could be noticed. The printing is still legible (tested with ribbons Armor AXR7+, AXR8, Ricoh B110CR, DNP R300, R510 and Iimak SP330).

### Chemical Resistance:

The performance results are based on simulation of a typical PCB cleaning process including a simulation of a solder process. Each cleaning process cycle was performed 3 times.

| Cleaning agent | Cleaner agent base | Process | Wash time (min) | Temp. (°C) | Rinse time (min) | Hot air drying 80°C (min) | Visual appearance |
|---|---|---|---|---|---|---|---|
| Atron® AC205 (15%)[1] | Water | spray-in-air | 15 | 65 | 5 | 30 | no change |
| Atron® AC207 (15%)[1] | Water | spray-in-air | 15 | 65 | 5 | 30 | no change |
| Vigon® A200 (30%)[1] | Water | spray-in-air | 15 | 65 | 5 | 30 | no change |
| Vigon® A201 (20%)[1] | Water | spray-in-air | 15 | 65 | 5 | 30 | no change |
| Vigon® A250 (30%)[1] | Water | spray-in-air | 15 | 65 | 5 | 30 | no change |
| Vigon® N600 (20%)[1] | Water | spray-in-air | 15 | 65 | 5 | 30 | no change |
| Vigon® US (30%)[1] | Water | ultrasonic | 15 | 65 | 5 | 30 | no change |
| Zestron® FA+[1] | Solvent | ultrasonic | 15 | 60 | 5 | 30 | no change |
| Zestron® VD[1] | Solvent | ultrasonic | 15 | 45 | steam rinsed | vacuum dried | no change |

**Chemicals** [1] Zestron Europe, a Business Division of Dr. O.K. Wack Chemie GmbH

## Appendix

### Thermal Transfer Printing:

#### Printability – Physical Resistance

Flat head printers (tests were performed with the printer Zebra XII 140):

| Ribbon | Settings speed | energy | Print Quality | ANSI Grade | Scratch resistance | Tape resistance |
|---|---|---|---|---|---|---|
| Armor AXR7+ | 3 | 30 | ++ | A | ++ | + |
| Armor AXR8 | 3 | 25 | ++ | A | ++ | + |
| DNP R300 | 6 | 25 | ++ | A | ++ | + |
| DNP R510 | 3 | 30 | ++ | A | ++ | + |
| Ricoh B110CR | 3 | 25 | ++ | A | ++ | + |

ANSI (American National Standards Institute) Grade: information about barcode quality
A: excellent B: good C: acceptable D: readable with difficulty
++: excellent +: good o: acceptable -: poor

#### Chemical Resistance

The printed samples passed a simulation of a solder process, followed by typical PCB cleaning processes (3 cycles), as described on the previous page. Afterwards the evaluation took place.

| | AXR7+ | AXR8 | R300 | R510 | B110CR |
|---|---|---|---|---|---|
| Atron® AC205 (15%) | + | + | + | + | + |
| Atron® AC207 (15%) | + | + | + | + | + |
| Vigon® A200 (30%) | + | + | + | + | + |
| Vigon® A201 (20%) | + | + | + | + | + |
| Vigon® A250 (30%) | + | + | + | + | + |
| Vigon® N600 (20%) | + | + | + | + | + |
| Vigon® US (30%) | + | + | + | + | + |
| Zestron® FA+ | + | + | + | + | + |
| Zestron® VD | + | + | + | + | + |

+: good (no change) o: acceptable (minor change, still readable) -: poor

**Chemicals:**
Zestron Europe, a Business Division of Dr. O.K. Wack Chemie GmbH

## Appendix

### Compliance Data

**UL – Underwriters Laboratories (UL 969, Category PGJI2)**

File Number: MH27538, Category PGJI2

This material is UL recognized for indoor use where exposed to high humidity or occasional exposure to water.

| Application Surface | Max Temp (°C) | Min Temp (°C) |
|---|---|---|
| Alkyd paint | +150 | -40 |
| Aluminum | +150 | -40 |
| Epoxy | +150 | -40 |
| Galvanized steel | +150 | -40 |
| Stainless steel | +150 | -40 |

The UL certification includes the printing with the following thermal transfer ribbons:
Armor “AXR7+”, “AXR 8”, “AXR EL”, DNP "R-510" and "R-300", Ricoh B110CR.

Avery Dennison Materials Group Europe
Willem Einthovenstraat 11
2342 BH Oegstgeest
The Netherlands
+31 (0)85 000 2000

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